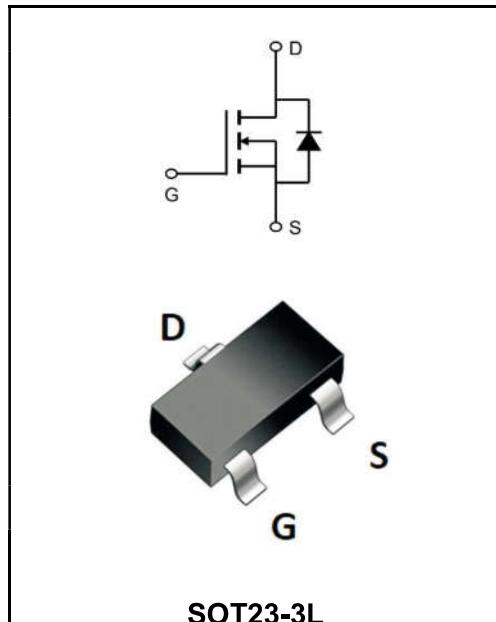


**200V N-CHANNEL ENHANCEMENT MODE MOSFET**
**MAIN CHARACTERISTICS**

$I_D$	3.8A
$V_{DSS}$	200V
$R_{DS(on)-typ}(@V_{GS}=10V)$	< 580mΩ (Type: 450 mΩ)


**Application**

- ◆Automotive lighting
- ◆Load switch
- ◆Uninterruptible power supply

<b>Marking Code</b>	
YFW4N20MI	YFW4N20MIXXXXX

**Maximum Ratings at  $T_c=25^\circ C$  unless otherwise specified**

Characteristics	Symbols	Value	Units
Drain-Source Voltage	$V_{DS}$	200	V
Gate - Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current, $V_{GS} @ 10V$ @ $T_c=25^\circ C$	$I_D$	3.8	A
Drain Current, $V_{GS} @ 10V$ @ $T_c=100^\circ C$	$I_D$	1.85	A
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	10	A
Total Power Dissipation @ $T_c=25^\circ C$	$P_D$	2	W
Total Power Dissipation <sup>3</sup> @ $T_A=25^\circ C$	$P_D$	1.1	W
Storage Temperature Range	$T_{STG}$	-55 to +150	°C
Operating Junction Temperature Range	$T_J$	-55 to +150	°C
Maximum Thermal Resistance, Junction ambient	$R_{\theta JA}$	85	°C/W
Maximum Thermal Resistance, Junction-case	$R_{\theta JA}$	3.9	°C/W

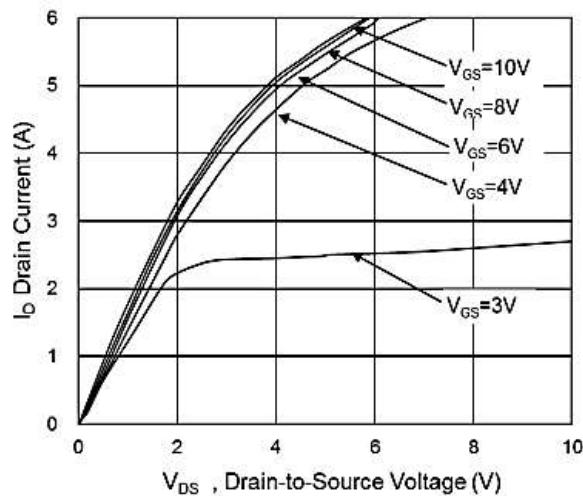
**Maximum Ratings at T<sub>c</sub>=25°C unless otherwise specified**

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	BV <sub>DSS</sub>	200	230	-	V
Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =1A	R <sub>DS(ON)</sub>	-	450	580	mΩ
	V <sub>GS</sub> =4.5V, I <sub>D</sub> =1A		-	680	850	
Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	V <sub>GS(th)</sub>	1.2	2	2.5	V
Drain-Source Leakage Current	V <sub>DS</sub> =200V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	I <sub>DSS</sub>	-	-	1	μA
Gate- Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	I <sub>GSS</sub>	-	-	±100	nA
Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =1V	g <sub>fs</sub>	-	10	-	S
Total Gate Charge(10V)	V <sub>DS</sub> =160V V <sub>GS</sub> =10V I <sub>D</sub> =1A	Q <sub>g</sub>	-	15	-	nC
Gate-Source Charge		Q <sub>gs</sub>	-	3.0	-	
Gate-Drain Charge		Q <sub>gd</sub>	-	5.2	-	
Turn-on delay time	V <sub>DD</sub> =100V V <sub>GS</sub> =10V R <sub>G</sub> =3 I <sub>D</sub> =1A	t <sub>d(on)</sub>	-	22	-	ns
Rise Time		T <sub>r</sub>	-	34	-	
Turn-Off Delay Time		t <sub>d(OFF)</sub>	-	45	-	
Fall Time		t <sub>f</sub>	-	11	-	
Input Capacitance	V <sub>DS</sub> =25V V <sub>GS</sub> =0V f=1MHz	C <sub>iss</sub>	-	900	-	pF
Output Capacitance		C <sub>oss</sub>	-	130	-	
Reverse Transfer Capacitance		C <sub>rss</sub>	-	4.6	-	
Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	I <sub>s</sub>	-	-	1	A
Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>s</sub> =1A, T <sub>J</sub> =25°C	V <sub>SD</sub>	-	-	1	V
Reverse Recovery Time	I <sub>F</sub> =1A, dI/dt=100A/μs, T <sub>J</sub> =25°C	t <sub>rr</sub>	-	85	-	ns
Reverse Recovery Charge		Q <sub>rr</sub>	-	257	-	nC

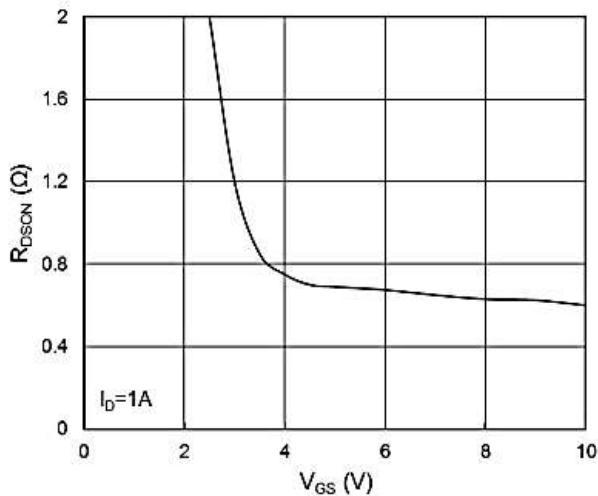
Note :

1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
3. The power dissipation is limited by 150°C junction temperature
4. The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.

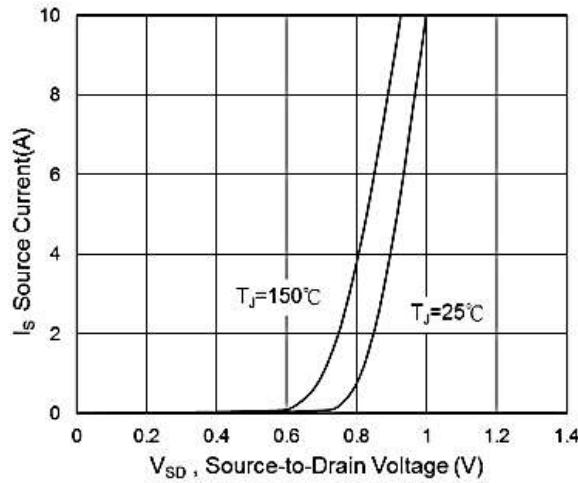
**Ratings and Characteristic Curves**



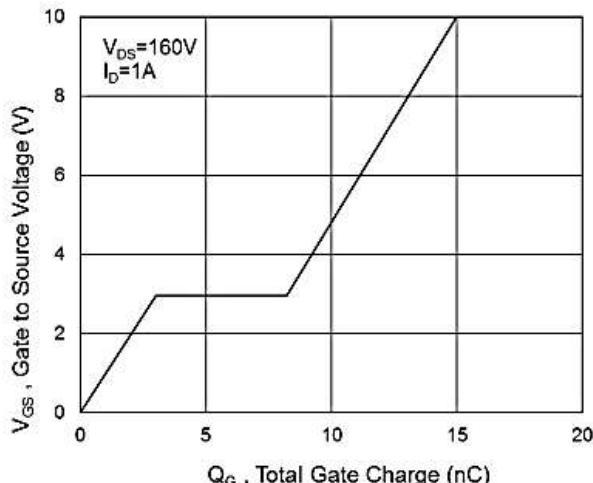
**Fig.1 Typical Output Characteristics**



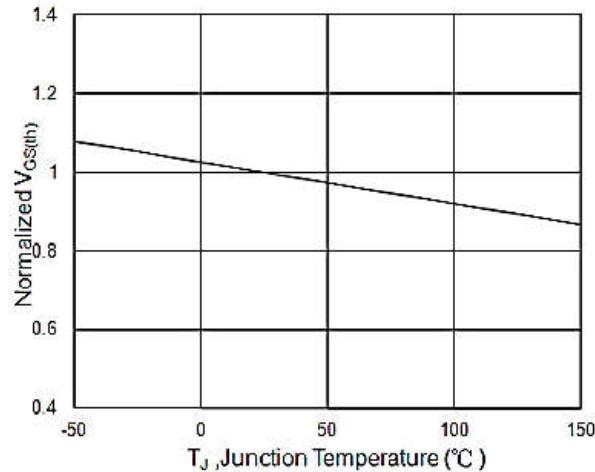
**Fig.2 On-Resistance vs. G-S Voltage**



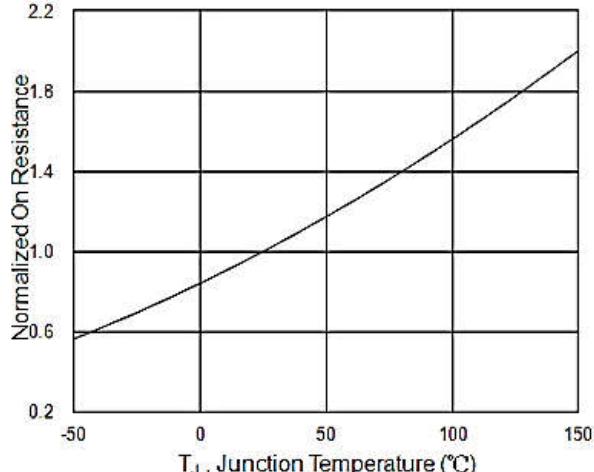
**Fig.3 Forward Characteristics of Reverse**



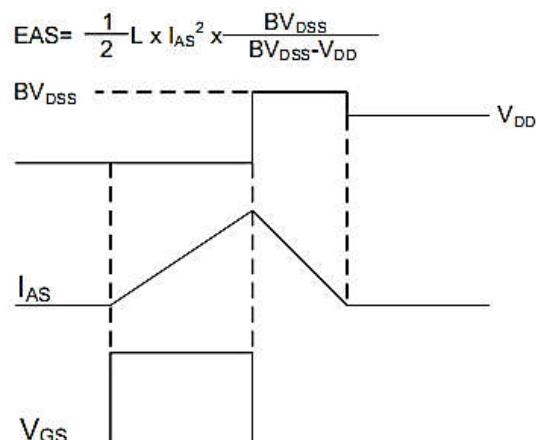
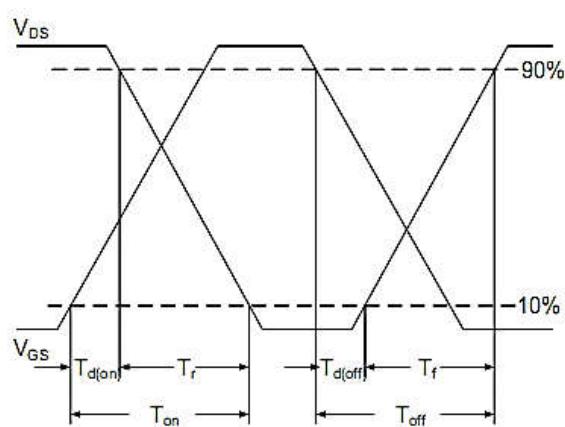
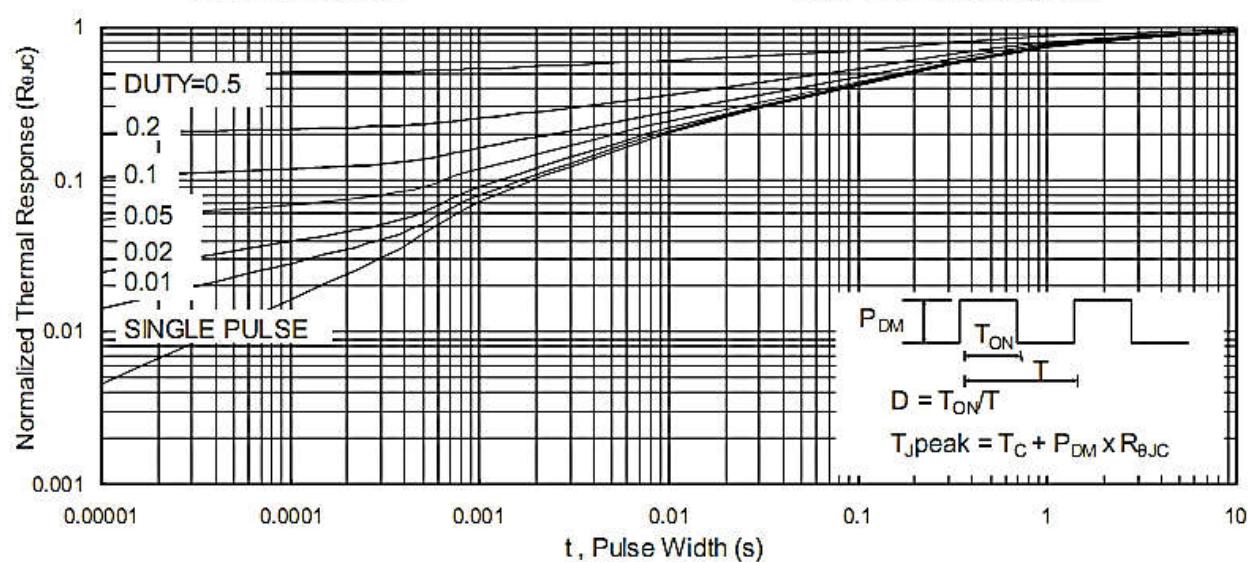
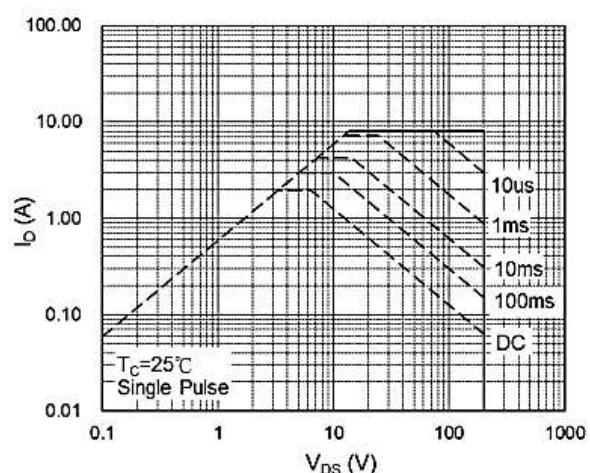
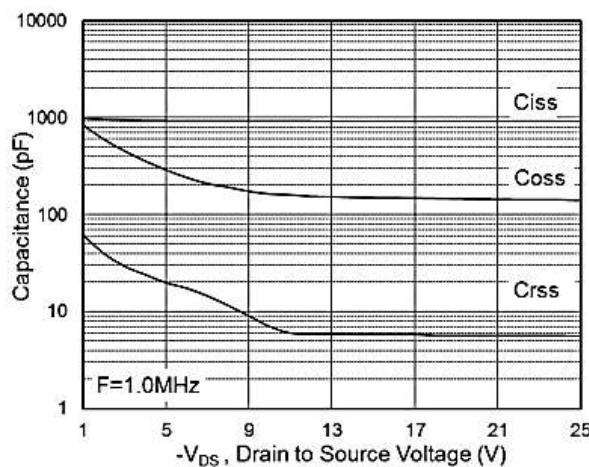
**Fig.4 Gate-Charge Characteristics**



**Fig.5  $V_{GS(th)}$  vs.  $T_J$**



**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**

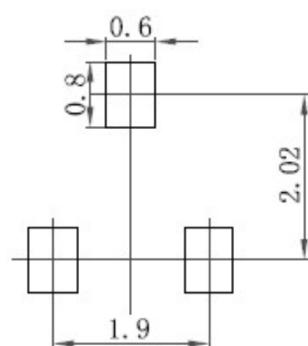
**Ratings and Characteristic Curves**


**Ordering information**

Package	Packing Description	Base Quantity	Packing Quantity
SOT23-3L	Tape/Reel,7"reel	3000pcs/Reel	24000PCS/Box 120000PCS/Carton

**Package Dimensions**
**SOT23-3L**

Dim.	Millimeter (mm)		mil	
	Min.	Max.	Min.	Max.
A	1.05	1.25	41	49.2
A1		0.10		3.93
A2	1.05	1.15	41	45
b	0.30	0.50	12	20
c	0.10	0.20	3.93	7.9
D	2.82	3.02	111	119
E	1.50	1.70	59	67
E1	2.65	2.95	104	116
e		0.95		37.4
e1	1.80	2.00	71	78
L	0.30	0.066	12	26
Θ			8°	

**The recommended mounting pad size**


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